PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7204204

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
CHI-WEN PAN	12/04/2018	

RECEIVING PARTY DATA

Name:	MEDIATEK INC.
Street Address:	NO. 1, DUSING RD. 1ST
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU 300
State/Country:	TAIWAN
Postal Code:	R.O.C.

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17685303

CORRESPONDENCE DATA

Fax Number: (617)646-8646

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 617-646-8000

Email: rjensen@wolfgreenfield.com, ekapo@wolfgreenfield.com

Correspondent Name: WOLF, GREENFIELD & SACKS, P.C.

Address Line 1: 600 ATLANTIC AVENUE

Address Line 4: BOSTON, MASSACHUSETTS 02210

ATTORNEY DOCKET NUMBER:	M1295.70350US01
NAME OF SUBMITTER:	EILEEN M. MACKENZIE
SIGNATURE:	/Eileen M. MacKenzie/
DATE SIGNED:	03/02/2022

Total Attachments: 10

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PATENT 507157359 REEL: 059152 FRAME: 0667

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> PATENT REEL: 059152 FRAME: 0668

Title of Invention: SEMICONDUCTOR PACKAGE HAVING A STIFFENER RING

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or	ſ		
☐ United States application no	ımber	filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	s made or authorized to b	e made by me.	
I believe that I am the original inventapplication.	or or an original joint inv	entor of a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	MEDIATEK INC.	having a postal	address of
No. 1, Dusing Rd. 1st, Scienc	e-Based Industrial P	ark, Hsin-Chu 300, Taiwan,	R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good as			s hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified application of substitutes, or extensions thereof, as	nd to any and all improve ation and, in and to, all Le r any continuations, cont	ements which are disclosed in the etters Patent to be obtained for sa inuation-in-part, divisions, renewa	id Is,
I hereby covenant that no assignme entered into which would conflict wit		ncumbrance has been or will be m	ade or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exe	ntion and said Letters Pa estify as to the same in a	tent and legal equivalents as may ny interference, litigation proceedi	be .
representatives any and all papers, maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention a ecessary or desirable to	and said Letters Patent and said carry out the proposes thereof.	
Note: An application data sheet (PT inventive entity, must accompany the			

Page 1 of 10

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chi-Wen Pan

Date:

2018.12.04

Signature: /

UI-WEN PAN

Page 2 of 10

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US F#NPO-P0002E-US1201 DSB0-107U037098

PATENT REEL: 059152 FRAME: 0670

Title of Invention: SEMICONDUCTOR PACKAGE HAVING A STIFFENER RING

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or	•			
☐ United States application nu	ımber	filed on	*	, or
☐ PCT international application	n number	filed	on	
The above-identified application was	s made or authorized t	o be made by me.		
I believe that I am the original invent application.	or or an original joint i	nventor of a claimed	nvention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				
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No. 1, Dusing Rd. 1st, Scienc	e-Based Industria	l Park, Hsin-Chu	300, Taiwan, R.	o.c.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			ceipt of which is he	ereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica invention by the above application o substitutes, or extensions thereof, a	nd to any and all impr ation and, in and to, all r any continuations, co	ovements which are of Letters Patent to be ontinuation-in-part, div	lisclosed in the obtained for said risions, renewals,	IEE
I hereby covenant that no assignme entered into which would conflict wit		encumbrance has be	en or will be made	or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will to related thereto and will promptly exe	ntion and said Letters estify as to the same in	Patent and legal equi any interference, liti	valents as may be	
representatives any and all papers, maintain, issue and enforce said ap equivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, sald inventio acessary or desirable	n and said Letters Pa to carry out the propo	tent and said ses thereof.	
Note: An application data sheet (PT inventive entity, must accompany th				

Page 3 of 10

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: I-Hsuan Peng Date:

MTN07867 2016/12/04 16:07:44

12. 4. 2018

Signature: 1- Hsuan Peng

Page 4 of 10

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US F#NPO-P0002E-US1201 DSB0-107U037098

PATENT REEL: 059152 FRAME: 0672

Title of Invention: SEMICONDUCTOR PACKAGE HAVING A STIFFENER RING

As the below named inventor, I here This declaration is directed to: The attached application, or			
☐ United States application nu		filed on	, or
☐ PCT international applicatio	n number	filed on	
The above-identified application was	made or authorized to b	e made by me.	
I believe that I am the original invent application.	or or an original joint inve	entor of a claimed invention	in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			ible
In consideration of the payment by	MEDIATEK INC.	having a	postal address of
No. 1, Dusing Rd. 1st, Science	e-Based Industrial P	ark, Hsin-Chu 300, Ta	iwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			vhich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, as	nd to any and all improve ition and, in and to, all Le r any continuations, cont	ements which are disclosed atiers Patent to be obtained inuation-in-part, divisions, r	in the for said enewals,
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;			
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal			
representatives any and all papers, maintain, issue and enforce said ap- equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention a acessary or desirable to d	and said Letters Patent and carry out the proposes there	said ∍of.
Note: An application data sheet (PT inventive entity, must accompany th			

Page 5 of 10

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Sheng-Liang Kuo

Date:

2018.12.10

Signature:

Page 6 of 10

Title of Invention: SEMICONDUCTOR PACKAGE HAVING A STIFFENER RING

As the below named inventor, I hereb This declaration is directed to:	y declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	number	filed on	
The above-identified application was	made or authorized to be r	nade by me.	
I believe that I am the original invento application.	or or an original joint invent	or of a claimed invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in the sonment of not more than t	is declaration is punishable live (5) years, or both.	
In consideration of the payment by	MEDIATEK INC.	having a postal	address of
No. 1, Dusing Rd. 1st, Science	-Based Industrial Par	k, Hsin-Chu 300, Taiwan,	R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	I of the sum of One Dollar d valuable consideration.	(\$ 1.00), the receipt of which is	s hereby
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified application or substitutes, or extensions thereof, an	ed to any and all improveme tion and, in and to, all Lette any continuations, continu	ents which are disclosed in the ers Patent to be obtained for sa lation-in-part, divisions, renewa	id als,
I hereby covenant that no assignmer entered into which would conflict with	it, sale, agreement or encu n this assignment;	mbrance has been or will be m	nade or
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal			
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	dication, said invention and cessary or desirable to car	I said Letters Patent and said ry out the proposes thereof.	
Note: An application data sheet (PTC inventive entity, must accompany thi	D/SB/14 or equivalent), incl s form. Use this form for <u>ex</u>	uding naming the entire ach additional inventor.	

Page 7 of 10

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Yi-Jou Lin

Date:

20/8/1-/4

Signature:

MTN07867 2016/12/04 16:07:44

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COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: SEMICONDUCTOR PACKAGE HAVING A STIFFENER RING

MINOTUS? 2018/12/04 16:07:44

As the below named inventor, I herel This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application number		filed on	, or
☐ PCT international application number		filed on	
The above-identified application was	made or authorized to be	made by me.	
I believe that I am the original invent application.	or or an original joint inven	tor of a claimed invention in l	ihe
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		r (\$ 1.00), the receipt of whic	h is hereby
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I hereby covenant that no assignmer entered into which would conflict will		umbrance has been or will be	e made or
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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and ecessary or desirable to ca	d said Letters Patent and sai rry out the proposes thereof.	
Note: An application data sheet (PT0 inventive entity, must accompany thi			

Page 9 of 10

MIK07867 2018/13/04 16:07:44

Inventor: Tal-Yu Chen

Date: 20/8.12.06

Signature: Tac-Yu Chen

NPO#MTK-P3315-USA:4 CUST#MTKI-18-782US

RECORDED: 02/02/2022

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F#NPO-P0002E-US1201 DSB0-107U037098

PATENT REEL: 059152 FRAME: 0678

Docket No MTKP3315USA4